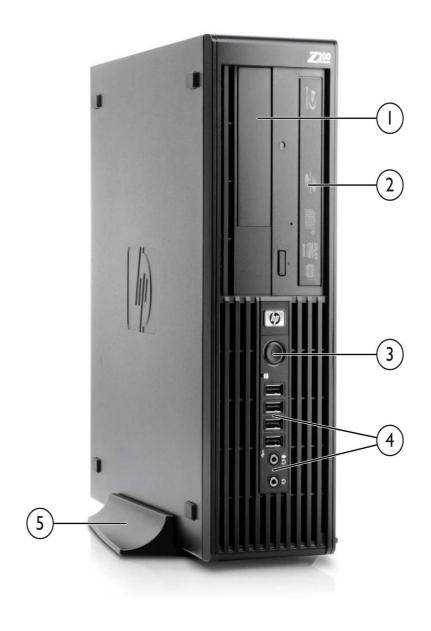
Overview



- 1. External 3.5" Bay
- 2. External 5.25" Bay
- 3. Power button
- 4. Standard Front I/O: 4 USB 2.0, headphone, microphone
- 5. Tower stand (optional)

Form Factor Small Form Factor



Overview

Compatible Operating Systems

Genuine Windows® 7 Ultimate 64-bit

Genuine Windows® 7 Professional 32-Bit Genuine Windows® 7 Professional 64-Bit

Genuine Windows® 7 Professional 32-bit Downgrade to Genuine Microsoft® Windows® XP Professional 32-bit Genuine Windows® 7 Professional 64-bit Downgrade to Genuine Microsoft® Windows® XP Professional 64-bit

NOTES: Systems may require upgraded and/or separately purchased hardware and/or DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality. See http://www.microsoft.com/windows/windows-7/ for details.

HP Linux Installer Kit for Linux (includes drivers for both 32-bit & 64-bit OS versions of Red Hat Enterprise Linux and WS5 and 64-bit Novell SLED 11 – see: http://www.hp.com/workstations/software/linux)

Novell SLED 11 Linux Preloaded

Red Hat Enterprise Linux WS5 (as Drop-in-the-box only)

For detailed OS/hardware support information for Linux, see: http://www.hp.com/support/linux hardware matrix

Available Processors

Intel® Pentium® processor G6950, 2.80 GHz, 73W, 3 MB cache, 1066 MHz memory, Dual-Core Intel® Core™ processor i3-530, 2.93 GHz, 73W, 4 MB cache, 1333 MHz memory, Dual-Core, HT Intel Core processor i3-540, 3.06 GHz, 73W, 4 MB cache, 1333 MHz memory, Dual-Core, HT Intel Core processor i3-550, 3.20 GHz, 73W, 4 MB cache, 1333 MHz memory, Dual-Core, HT Intel Core processor i5-650, 3.20 GHz, 73W, 4 MB cache, 1333 MHz memory, Dual-Core, HT, Turbo Intel Core processor i5-660, 3.33 GHz, 4 MB cache, 1333 MHz memory, Dual-Core, HT, Turbo Intel Core processor i5-670, 3.46 GHz, 73W, 4 MB cache, 1333 MHz memory, Dual-Core, HT, Turbo Intel Core processor i5-680, 3.60 GHz, 73W, 4 MB cache, 1333 MHz memory, Dual-Core, HT, Turbo Intel Core processor i5-750, 2.66 GHz, 95W, 8 MB cache, 1333 MHz memory, Quad-Core, Turbo Intel Core processor i7-870, 2.93 GHz, 95W, 8 MB cache, 1333 MHz memory, Quad-Core, HT, Turbo Intel Core processor i7-880, 3.06 GHz, 95W, 8 MB cache, 1333 MHz memory, Quad-Core, HT, Turbo Intel® Xeon® processor X3430, 2.40 GHz, 95W, 8 MB cache, 1333 MHz memory, Quad-Core, Turbo Intel Xeon processor X3440, 2.53 GHz, 95W, 8 MB cache, 1333 MHz memory, Quad-Core, HT, Turbo Intel Xeon processor X3450, 2.66 GHz, 95W, 8 MB cache, 1333 MHz memory, Quad-Core, HT, Turbo Intel Xeon processor X3460, 2.80 GHz, 95W, 8 MB cache, 1333 MHz memory, Quad-Core, HT, Turbo Intel Xeon processor X3470, 2.93 GHz, 95W, 8 MB cache, 1333 MHz memory, Quad-Core, HT, Turbo Intel Xeon processor X3480, 3.06 GHz, 95W, 8 MB cache, 1333 MHz memory, Quad-Core, HT, Turbo

Available Processor Disclaimers

Integrated Intel HD graphics is not supported on the Quad-Core Intel Core i5-700 Desktop Processor Series, Intel Core i7-800 Desktop Processor Series or Intel Xeon Processor 3400 Series.

Intel's numbering is not a measurement of higher performance. Processor numbers differentiate features within each processor family, not across different processor families. See: http://www.intel.com/products/processor_number/ for details.

64-bit computing on Intel® 64 architecture requires a computer system with a processor, chipset, BIOS, operating system, device drivers and applications enabled for Intel 64 architecture. Processor will not operate (including 32-bit operation) without an Intel 64 architecture-enabled BIOS. Performance will vary depending on your hardware and software configurations. See: http://www.intel.com/info/em64t for more information.

Dual-Core and Quad-Core technologies are designed to improve performance of multithreaded software products and hardware-aware multitasking operating systems and may require appropriate operating system software for full benefits; check with software provider to determine suitability; Not all customers or software applications will necessarily benefit from use of these technologies.

Color

Jack Black

Convertibility The Z200 SFF can either be placed flat on the desktop or made to stand on the desk with the optional tower stand.



Overview

Overview					
Expansion Slots (see system board section for more details) Expansion	1 PCI Express Gen2 slot x16 m1 PCI Express Gen1 slot x16 m1 PCI slot (Low Profile)	chanical/x1 electrical (Low Profile) echanical/ x16 electrical (Low Profile, dedicated for graphics) echanical/x4 electrical (Low Profile)			
Bays (see storage section for more details)	• 1 external 5.25" bay.				
	audio out, and 1 microphone/ 2nd he				
Internal I/O	4 USB 2.0 ports available by two sepa	arate 9-pin headers			
Rear I/O		Intel HD graphics (available on dual-core processors only); 6 USB 2.0, 1 standard parallel port, 2 PS/2, RJ-45 (NIC), 1 audio line in, 1 audio line out; audio ports line out, microphone, or headphone			
Interfaces Supported	22-in-1 Media Card Reader (optional				
Chassis Dimensions (W x D x H)	· ·	n x 338mm x 381mm (HxWxD) (3.95" x13.3" x15.0"); ding stand dimension): 338mm x 100mm x 381mm (HxWxD) (13.3" x3.95"			
Weight	Exact weights depend upon configuration; System Weight* 7.6 kg (16.72 lbs) Shipping Weight* 8.1 kg (17.86 lbs) Max Supported Weight (desktop orientation) 35 kg (77 lb) *Configured with 1 hard drive, 1 optical drive and one NVIDIA Quadro NVS 295 low profile graphics card.				
Temperature	Operating:	40° to 95°F (5° to 35°C)			
	Non-operating	-40° to 140°F (-40° to 60°C)			
Humidity	Operating:	8% to 85%			
litioning	Non-operating	8% to 90%			
Maximum Altitude	Operating:	10,000 feet; 3,000 m			
(non- pressurized)	Non-operating	30,000 feet; 9,100 m			
Power Supply	240 watts wide-ranging, active Power Factor Correction, 89% Efficient The Power Supply Efficiency Report for this product may be found at these links: http://www.80plus.org/manu/psu/psu_reports/HEWLETT%20PACKARD_PC80190_ECOS%201587_240W_Report.pdf; http://www.80plus.org/manu/psu/psu_reports/HEWLETT%20PACKARD_HP- 2402E0_ECOS%201586_240W_Report.pdf; http://www.80plus.org/manu/psu/psu_reports/HEWLETT%20PACKARD_PS-4241- 9HA_ECOS%201588_240W_Report.pdf				
Backup Devices	For a complete listing of compatible Deferings, please visit http://www.hp.c	OAT tape drives, LTO tape drives and RDX Removable Disk Backup System om/go/connect			



Supported Components

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Dual-Core Intel® "Clarkdale" Processors for Z200				
	Intel® Pentium® Processor G6950 2.8 GHz, 3MB cache, 1066 MHz memory, Dual-Core	Υ	Ν		
	Intel® Core™ Processor i3-530 2.93 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT	Υ	Ν		
	Intel Core Processor i3-540 3.06 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT	Υ	Ν		
	Intel Core Processor i3-550 3.20 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT	Υ	Ν		
	Intel Core Processor i5-650 3.20 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT, Turbo	Υ	Ν		
	Intel Core Processor i5-660 3.33 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT, Turbo	Υ	Ν		
	Intel Core Processor i5-670 3.46 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT, Turbo	Υ	Ν		
	Intel Core Processor i5-680 3.60 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT, Turbo	Υ	Ν		
	Quad-Core Intel® Core™ i5-700 and Core i7-800 Desk	top Processor	Series		
	Intel Core Processor i5-750 2.66 GHz, 8 MB cache, 1333 MHz memory, Quad-Core, Turbo	Υ	Ν		
	Intel Core Processor i7-870 2.93 GHz, 8 MB cache, 1333 MHz memory, Quad-Core, HT, Turbo	Υ	Ν		
	Intel Core Processor i7-880 3.06 GHz, 8 MB cache, 1333 MHz memory, Quad-Core, HT, Turbo	Υ	Ν		
	Quad-Core Intel® Xeon® Processor 3400 Series with Inte	el® Nehalem	Architectu	ıre	
	Intel Xeon Processor X3430 2.40 GHz, 8MB cache, 1333 MHz memory, Quad-Core, Turbo	Υ	Ν		
	Intel Xeon Processor X3440 2.53 GHz, 8MB cache, 1333 MHz memory, Quad-Core, HT, Turbo	Υ	Ν		
	Intel Xeon Processor X3450 2.66 GHz, 8MB cache, 1333 MHz memory, Quad-Core, HT, Turbo	Υ	Ν		
	Intel Xeon Processor X3460 2.80 GHz, 8MB cache, 1333 MHz memory, Quad-Core, HT, Turbo	Υ	Ν		
	Intel Xeon Processor X3470 2.93 GHz, 8MB cache, 1333 MHz memory, Quad-Core, HT, Turbo	Υ	Ν		
	Intel Xeon Processor X3480 3.06 GHz, 8MB cache, 1333 MHz memory, Quad-Core, HT, Turbo	Υ	Ν		

Integrated Intel® HD graphics is supported only on Dual-Core Intel® "Clarkdale" Processors; it is not supported on the Quad-Core Intel Core i5-700 Desktop Processor Series, Intel Core i7-800 Desktop Processor Series or Intel Xeon Processor 3400 Series



Supported Components

SATA Hard Drives		Factory Configured	Option Kit		Support Notes
	SATA (Serial ATA) Hard Drives for HP Workstations				
	160GB SATA 7200 rpm 3Gb/s 3.5" HDD	Υ	Υ	PV944A	
	250GB SATA 7200 rpm 3Gb/s 3.5" HDD (for HP Z-Workstations)	Υ	Υ	PY278AA	
	320GB SATA 7200 rpm 3Gb/s 3.5" HDD	Υ	Υ	FH963AA	
	500GB SATA 7200 rpm 3Gb/s 3.5" HDD	Υ	Υ	PV943A	
	1000GB (1TB) SATA 7200 rpm 3.0Gb/s 3.5" HDD	Υ	Υ	GE262AA	
	300GB SATA 10K rpm SFF in 3.5" Frame HDD	Υ	Υ	FM802AA	
	160GB SATA 10K rpm SFF in 3.5" Frame HDD	Υ	Υ	EW222AA	

Hard Drive Controllers	Opti Factory I				C N	
		Configured	Option Kit	Number	Support Notes	
	Integrated SATA 3.0 Gb/s Controller					
	Integrated SATA 3.0 Gb/s Controller	Υ	Ν			
	Factory integrated RAID on motherboard for SATA	drives				
	RAID 0 Configuration – Striped Array	Υ	Ν		Available May 2010	
	RAID 1 Configuration – Mirrored Array	Υ	Ν			

RAID 0 availability May 2010.

SATA hardware RAID is not supported on Linux systems. The Linux kernel, with built-in software RAID, provides excellent functionality and performance. It is a good alternative to hardware-based RAID. Please visit http://h20000.www2.hp.com/bc/docs/support/SupportManual/c00060684/c00060684.pdf for RAID capabilities with Linux.

All drives must be identical in type and capacity

All RAID arrays must be less than 2 TB

NOTE 1: Requires identical hard drives (speeds, capacity, interface).

Integrated Graphics		Factory Configured	Option Kit	Option Kit Part Number	Support Notes	Supported Multi Mixed
	Intel® HD Graphics	Υ	Ν			1
	Professional 2D					
	NVIDIA Quadro NVS 295 256MB PCle Graphics Card	Υ	Υ	FY943AA		2 X
	Entry 3D					
	NVIDIA Quadro FX 380 LP 512MB PCle Graphics Card	Υ	Y	WL055AA		1
	ATI FirePro V3800 512MB PCle Graphics Card	Y	Υ	WL048AA		1



Supported Components

Memory	СТО	Option Kit Part Number	Support Notes
	PC3-10600 DDR3-1333 ECC Unbuffered DIMMs CTO		
	2GB (2x1GB) DDR3-1333 ECC Unbuffered RAM 1-CPU		
	3GB (3x1GB) DDR3-1333 ECC Unbuffered RAM 1-CPU		
	4GB (2x2GB) DDR3-1333 ECC Unbuffered RAM 1-CPU		
	8GB (4x2GB) DDR3-1333 ECC Unbuffered RAM 1-CPU		
	8GB (2x4GB) DDR3-1333 ECC Unbuffered RAM 1-CPU		
	16GB (4x4GB) DDR3-1333 ECC Unbuffered RAM 1-CPU		
	PC3-10600 DDR3-1333 nECC Unbuffered DIMMs CTO		
	1 GB (1x1GB) DDR3-1333 nECC Unbuffered RAM 1-CPU		
	2 GB (2x1GB) DDR3-1333 nECC Unbuffered RAM 1-CPU		
	4 GB (2x2GB) DDR3-1333 nECC Unbuffered RAM 1-CPU		
	8 GB (4x2GB) DDR3-1333 nECC Unbuffered RAM 1-CPU		
	Sub-Section Description/Notes		
	Two channels of DDR3 memory are supported. To realize full p	erformance at least on	e DIMM must be

Two channels of DDR3 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.

The CPUs determine the speed at which the memory is clocked. If a 1066 MHz capable CPU is used in the system, the maximum speed the memory will run at is 1066 MHz regardless of the specified speed of the memory.

AMO

PC3-10600 DDR3-1333 ECC Unbuffered DIMMs AMO

4GB (1x4GB) DDR3-1333 ECC Unbuffered RAMNL797AA2GB (1x2GB) DDR3-1333 ECC Unbuffered RAMFX699AA1GB (1x1GB) DDR3-1333 ECC Unbuffered RAMFX698AA

NOTE: Only unbuffered DDR3 DIMMs are supported.

Multimedia and Audio Devices		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Thin USB Powered Speakers	Υ	Υ	KK912AA	
	Integrated Intel/Realtek HD ALC261 Audio	Υ	Υ		



Supported Components

Optical and Removable Storage		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP 16X DVD-ROM SATA Drive	Υ	Υ	EW268AA	See note 1
	HP 16X DVD+-RW SuperMulti SATA Drive	Υ	Υ	EW269AA	
	HP 22-in-1 Media Card Reader Kit (Workstations)	Υ	Υ	NK361AA	
	HP Blu-ray Writer	Υ	Υ	AR482AA	
	HP 22-in-1 3.5 JackBlack Media Card Reader with 1394a	Υ	Υ		

Actual speeds may vary. Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players. As Blu-ray is a new format containing new technologies, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

NOTE 1: Not supported as a 2nd drive option.

Controller Cards	HP FireWire/IEEE 1394a PCI Card	Factory Configured Y	Option Kit Y	Option Kit Part Number	Support Notes
Monitors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP ZR24w 24" S-IPS LCD Monitor	Ν	Υ	VM633A8	
	HP ZR22w 21.5" S-IPS LCD Monitor	Ν	Υ	VM626A8	
	HP LP3065 30-inch Widescreen LCD Monitor	Ν	Υ	EZ320A	
	HP LP2475w 24-inch Widescreen LCD Monitor	Ν	Υ	KD911A	
	HP LP2275w 22-inch Widescreen LCD Monitor	Ν	Υ	KE289A	
	HP DreamColor LP2480zx Professional Display	Ν	Υ	GV546A	
	HP LP1965 19-inch LCD Monitor	Ν	Υ	RA373A	
	HP LP2065 20-inch LCD Monitor	Ν	Υ	EF227A	
	Supported by all Operating Systems available from HP				
	Screen Size Diagonally Measured				



Supported Components

Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Broadcom (5761) NetXtreme Gigabit Ethernet Plus NIC	N	Y		This is a PCI Express card based on the Broadcom 5761 chip.
	Intel Gigabit CT Desktop NIC	Υ	Υ		
	Integrated Intel 82578DM PCIe LoM Controller	Υ	Ν		

NOTE 1: "Gigabit" Ethernet indicates compliance with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

The Broadcom (5761) NetXtreme Gigabit Ethernet Plus NIC and the Intel Gigabit CT NIC are supported on the following operating systems:

Microsoft Windows XP Pro 32-bit and 64-bit and Microsoft Windows 7 32-bit and 64-bit versions. Red Hat Enterprise Linux(RHEL), 5 Desktop/Workstation

Novell SLED 10 & 11

Racking and Physical Security		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Security Cable with Kensington Lock	Ν	Υ	PC766A	
	HP Solenoid Hood Lock & Hood Sensor	Υ	Υ	GJ116AA	SFF
					version

Input Devices		Factory Configured	Option Kit	Option Kit Part Suppor Number Notes	
	HP USB Laser Mouse	Υ	Υ	GW405AA	
	HP SpaceExplorer 3D USB Controller	Ν	Υ	RY429AA	
	HP USB 2-Button Optical Scroll Mouse	Υ	Υ	DC172B	
	HP USB Standard Keyboard	Υ	Υ	DT528A	
	HP PS/2 Optical Scroll Mouse	Υ	Υ	EY703AA	
	HP PS/2 Standard Keyboard	Υ	Υ	DT527A	
	HP USB Optical 3-Button Mouse	Υ	Υ	DY651A	
	HP USB Smart Card Keyboard	Ν	Υ	ED707AA	
	HP 2.4GHz Wireless Keyboard & Mouse	Ν	Υ	NB896AA	



Supported Components

Other Hardware	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP Power Cord Kit	Ν	Υ	DM293A	
HP Workstation Mouse Pad	Υ	Ν		Japan only
HP Serial Port Adapter	Ν	Υ	PA716A	
HP ENERGY STAR 5.0 Enabled Configuration	Υ	Ν		
HP Parallel Port Adapter Kit	Ν	Υ	KD061AA	

Software		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intervideo WinDVD with DVD player	Υ	Ν		
	Microsoft Office 2007 Small Business Edition	Υ	Ν		
	Microsoft Office 2007 Trial Edition	Υ	Ν		
	PDF Complete - Trial Edition	Υ	Ν		
	Roxio Easy Media Creator (CD or DVD burner)	Υ	Ν		
	HP Client Manager Software v6.2 (optional download)	Υ	Ν		
	HP SkyRoom Software	Ν	Υ		Software is pre- installed.
	HP Support Assistant	Υ	Ν		

Operating Systems	Support Notes

Genuine Windows® 7 Ultimate 64-

HP Linux Installer Kit

Genuine Windows® 7 Professional

32-bit

Red Hat Linux Workstation 5 Drop

In Box OS

Genuine Windows® 7 Professional

32-bit with downgrade to

Windows® XP Professional 32-bit

custom installed

Genuine Windows® 7 Professional

64-bit

Novell SLED 11 Linux

Genuine Windows® 7 Professional

64-bit with downgrade to Windows® XP Professional x64

custom installed

See: http://www.hp.com/workstations/software/linux

See: http://www.microsoft.com/windows/windows-7/ for support

details.

See: http://www.microsoft.com/windows/windows-7/ for support

See: http://www.microsoft.com/windows/windows-7/ for support

details.

Preload

See: http://www.microsoft.com/windows/windows-7/ for support

details.



Supported Components

* Windows® 7 Professional 64-bit with downgrade to Windows® XP Professional x64 will be available May 2010



System Technical Specifications

System Board	
System Board Form Factor	BTX 21.2mm x 26.7mm
Processor Socket	Single LGA 1156
CPU Bus Speed	DMI
Chipset	Intel® PCH 3450
Super I/O Controller	SMSC SCH5327, Rev B
Memory Expansion Slots	4 DDR3 memory slots
Memory Type Supported	DDR3, UDIMM (Unbuffered), ECC & nECC
Memory Modes	Channel non-Interleaved
Memory Speed Supported	1333MHz DDR3
Memory Protection	ECC available on data, parity on address and command
Memory	
Maximum Memory	16GB

MEMORY LOADING CONFIGURATIONS

Memory	N 19		9	
Size (GB)	DIMM1	DIMM2	DIMM3	DIMM4
1	1 GB			v y
2	1 GB		1 GB	
3	1 GB	1 GB	1 GB	v i
4	2 GB		2 GB	
8	2 GB	2 GB	2 GB	2 GB
8	4 GB	1	4 GB	
16	4 GB	4 GB	4 GB	4 GB

Memory Configuration (Supported)	ECC DIMMs are supported, as well as non-ECC 1GBx1 configuration on Z200 SFF.		
PCI Express Connectors	1 PCI Express x16 Gen2 slot (x16 electrical/ mechanical) 1 PCI Express Gen1 slot x16 mechanical/x4 electrical 1 PCI Express Gen1 slot x1 mechanical/x1 electrical NOTES: Note: In the PCIe x16 Gen 2 slot, if it is not being used for a graphics card, only cards certified as After Market Options for this platform are supported.		
PCI Connectors (5.0V)	1 PCI		
Interfaces Supported	SATA Integrated (4) Serial ATA interfaces (Three common SATA ports and one that can optionally be used for eSATA). RAID Cand 1 supported. (Factory integrated RAID is Microsoft Windows only).		
Serial Attached SCSI	None		
Integrated RAID	NOTE: Requires identical hard drives (speeds, capacity, interface)		



cilications				
Integrated Intel HD Graphics Media Accelerator UMA (graphics frame buffer). Integrated graphics can support dual display across DP & VGA outputs.				
NOTES: Unified Memory Architecture (UMA)- A region of system memory is reserved and dedicated to the graphics display. DirectX 9.0 compliant 2D/3D graphics core 1 VGA + 1 DP graphics ports integrated in motherboard.				
Integrated Gbit LAN MAC by Intel PHY H and AMT 6.0	anksville 82578DM. Management capabilities WOL, PXE 2.1			
1 port eSATA capable with optional eSAT	A After-Market Option cable kit.			
No				
No				
Management capabilities WOL, PXE 2.1	and ASF 2.0			
1 rear port				
Yes- requires optional Serial Port Adaptor	r			
1 internal header (optional parallel port o	adaptor required)			
High Definition Integrated Realtek ALC26	1 Audio with Line in, Line Out, Microphone, Headphone			
No				
No				
Front	1 IEEE 1394a (requires optional PCI card to function)			
Rear	No			
Internal	No			
Front	4 USB 2.0			
Rear	6 USB 2.0			
Internal	4 USB 2.0			
Yes				
Not applicable – passive CPU heatsink				
Yes				
No				
Yes				
Yes				
Yes	Yes			
Integrated TPM 1.2				
Yes				
Yes				
Yes				
USB or PS/2				
240W, 89% efficiency				
90-264 VAC				
00-240 VAC				
	Integrated Intel HD Graphics Media Acce UMA (graphics frame buffer). Integrated of NOTES: Unified Memory Architecture (UI the graphics display. DirectX 9.0 complia integrated in motherboard. Integrated Gbit LAN MAC by Intel PHY H and AMT 6.0 1 port eSATA capable with optional eSAT No No Management capabilities WOL, PXE 2.1 1 rear port Yes- requires optional Serial Port Adapto 1 internal header (optional parallel port of High Definition Integrated Realtek ALC26 No No Front Rear Internal Front Rear Internal Yes Not applicable – passive CPU heatsink Yes No Yes Yes Yes Integrated TPM 1.2 Yes Yes USB or PS/2 240W, 89% efficiency 90-264 VAC			



Rated Line Frequency	50/60 Hz
Operating Line Frequency	
Range	
Rated Input Current	4A
Heat Dissipation	Typical 580 btu/hr (146 kg-cal/hr) Maximum 941 btu/hr (237 kg-cal/ hr)
Power Supply Fan	92x25 mm variable speed
ENERGY STAR® qualified (Config Dependent)	Yes
80 PLUS Compliant	Yes
FEMP Standby Power Compliant 115V (Wake- on LAN disabled) (<2W in S5 - Power Off)	Yes
Power consumption in sleep mode (as defined by ENERGY STAR) - Suspend to RAM (S3)	<5W
Built-in Self Test (BIST) LED	No
Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)	Yes
Hood Lock Header	Yes

Declared Noise Emissions (Entry-level and High-end configurations)				
System Configuration	Processor Info	Intel i5-670, 3.46 GHz		
(Entry level)	level) Memory Info 2 x 2GB DDR3 1333 MHz			
Graphics Info Integrated Graphics		Integrated Graphics		
Disks/Optical/Floppy 1 x 160 GB 7200 RPM SATA / DVD-ROM / No Floppy				

Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure
(in accordance with ISO	Idle	3.3 Bels	18.9 dB
7779 and ISO 9296)	SATA Hard drive Operating (random reads)	3.3 Bels	19.2 dB
	Floppy Drive Operating (continuous copy)	N/A	N/A
	DVD-ROM Operating (sequential reads)	4.8 Bels	35.3 dB



System Configuration	Processor Info	Intel Xeon Processor X3470 Lynnfield 2.93 GHz
(High-end)	Memory Info	4 x 2GB DDR3 1333 MHz
	Graphics Info	NVIDIA Quadro FX 380LP
	Disks/Optical/Floppy	2 x 500 GB 7200 SATA / DVD-ROM / No Floppy

Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure
(in accordance with ISO	Idle	3.5 Bels	20.4 dB
7779 and ISO 9296)	Hard drive Operating (random reads)	3.6 Bels	21.7 dB
	Floppy Drive Operating (continuous copy)	N/A	N/A
	DVD-ROM Operating (sequential reads)	5.0 Bels	36.9 dB

System Configuration					
Example Configuration	Processor Info	Intel Core i3-530 Processor 2.93GHz			
#1	Memory Info	2x 2GB DDR3 1333 (UDIMM)			
	Graphics Info	NVIDIA Quadro NVS295			
	Disks/Optical/Floppy	1x160GB SATA / 1 Optical			
	PSU	240W 89% Efficient			

Energy Consumption	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	41.0)2 W	42.63 W		41.63 W	
Windows Busy Typ (S0)	92.25 W		91.20 W		92.18 W	
Windows Busy Max (S0)	111.34 W		110.49 W		112.17 W	
Sleep (S3)	2.89 W	2.82 W	3.22 W	3.14 W	2.86 W	2.79W
Off (S5)	0.84 W	0.76 W	1.12 W	1.04 W	0.82 W	0.73 W
Zero Power Mode (EuP)	0.66 W		0.8	5 W	0.6	5W

Heat Dissipation**	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	139.96 btu/hr		145.46 btu/hr		142.05 btu/hr	
Windows Busy Typ (S0)	314.77 btu/hr		311.18 btu/hr		314.53 btu/hr	
Windows Busy Max (S0)	379.90) btu/hr	377.00 btu/hr		382.73 btu/hr	
Sleep (S3)	9.86 btu/hr	9.62 btu/hr	10.99 btu/hr	10.71btu/hr	9.76 btu/hr	9.52 btu/hr
Off (\$5)	2.87 btu/hr	2.59 btu/hr	3.82 btu/hr	3.55 btu/hr	2.80 btu/hr	2.49 btu/hr
Zero Power Mode (EuP)	2.25 btu/hr		2.90	btu/hr	2.22	btu/hr



System Configuration		
Example Configuration	Processor Info	1x Intel Xeon X3460 2.8GHz
#2	Memory Info	4x 2GB DDR3 1333MHz (UDIMM)
	Graphics Info	1x FX380 LP
	Disks/Optical/Floppy	1x 160GB SATA / 1 Optical
	PSU	240W 89% Efficient

Energy Consumption	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	39.0	3 W	40.19 W		39.60 W	
Windows Busy Typ (S0)	172.32 W		170.05 W		174.66 W	
Windows Busy Max (S0)	217.59 W		212.36 W		220.49 W	
Sleep (S3)	3.35 W	3.26 W	3.96 W	3.62 W	3.32 W	3.25 W
Off (S5)	0.84 W	0.75 W	1.12 W	1.04 W	0.82 W	0.73 W
Zero Power Mode (EuP)	0.66 W		0.8	5 W	0.6	5W

Heat Dissipation**	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	133.17	⁷ btu/hr	137.13 btu/hr		135.12 btu/hr	
Windows Busy Typ (S0)	587.97 btu/hr		580.23 btu/hr		595.96 btu/hr	
Windows Busy Max (S0)	742.44	ł btu/hr	724.59 btu/hr		752.33 btu/hr	
Sleep (S3)	11.4 btu/hr	11.1 btu/hr	13.5 btu/hr	12.3 btu/hr	11.3 btu/hr	11.1 btu/hr
Off (S5)	2.87 btu/hr	2.56 btu/hr	3.82 btu/hr	3.55 btu/hr	2.80 btu/hr	2.49 btu/hr
Zero Power Mode (EuP)	2.25 btu/hr		2.90	otu/hr	2.22	btu/hr

System Configuration					
#3 (ENERGY STAR Qualified)	Processor Info	1x Intel Xeon X3470 2.93GHz			
	Memory Info	4x 4GB DDR3 1333MHz (UDIMM)			
	Graphics Info	2x NVS295			
	Disks/Optical/Floppy	2x1000GB SATA / 1 Optical			
	PSU	240W 89% Efficient			

Energy Consumption	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
On-Idle (ENERGY STAR® Idle (S0))	62.40 W		62.05 W		62.42 W	
ENERGY STAR® "Sleep" (S3)	3.84 W	-	4.05 W	-	3.84 W	-
ENERGY STAR® "Standby" (Off) (S5)	0.87 W	-	1.03 W	-	0.86 W	



System Technical Specifications

Heat Dissipation**	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
On-Idle (ENERGY STAR® Idle (S0))	212.92 btu/hr		211.72 btu/hr		212.98 btu/hr	
ENERGY STAR® "Sleep" (S3)	13.1 btu/hr	-	13.8 btu/hr	-	13.1 btu/hr	-
ENERGY STAR® "Standby" (Off) (S5)	2.97 btu/hr	-	3.51 btu/hr	-	2.93 btu/hr	-

NOTES:

^{**} Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. This product is in compliance with US executive order 13221.

Environmental Requirements	Temperature	Operating: 40° to 95° F (5° to 35° C) Non-operating: -40° to 140° F (-40° to 60° C)
	Humidity	Operating: 8% to 85% RH, non-condensing Non-operating: 8% to 90% RH, non-condensing
	Maximum Altitude	Operating: 10,000 feet (3,000 m) Non-operating: 30,000 feet (9,100 m)
	Dynamic (new)	Shock Operating: ½-sine: 40g, 2-3ms Non-operating: ½-sine: 160 cm/s, 2-3ms (~100g) square: 422 cm/s, 20g Vibration Operating random: 0.5g (rms), 5-300 Hz Non-operating random: 2.0g (rms), 10-500 Hz NOTES: Values represent individual shock events and do not indicate repetitive shock events. Values do not indicate continuous vibration.
	Cooling	Above 5,000 ft (1524 m) altitude, maximum operating temperature is derated by 1.8° F (1° C) per 1,000 ft (305 m) elevation increase

Physical Security an	Physical Security and Serviceability		
	Tool-less Includes system board and memory information		
Expansion Cards	Tool-less		
Processor Socket	Tool-less, except for the processor heatsink.		
Green User Touch Points	Yes, on tool-free internal chassis mechanisms		
Color-coordinated Cables and Connectors	Yes		
Memory	Tool-less		
System Board	Screw-In		



^{*} Energy Star low energy mode

system rechnical spe	CHICUHOUS
Dual Color Power and HD LED on Front of Computer	Yes
Configuration Record SW	Yes
Over-Temp Warning on Screen	Yes
Restore CD/DVD Set	Restores the computer to its original factory shipping image - Can be obtained via HP Support
Dual Function Front Power Switch	Yes, causes a fail-safe power off when held for 4 seconds
Padlock Support	Yes (optional): Locks side cover and secures chassis from theft 0.22-in diameter padlock loop at rear of system
Cable Lock Support	Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft 3 mm x 7 mm slot at rear of system
Universal Chassis Clamp Lock Support	Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows multiple units to be chained together when used with optional cable Threaded feature at rear of system
Solenoid Lock and Hood Sensor	Yes (optional) The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through software and a password. You can also lock and unlock the chassis remotely over the network. The Sensor Kit detects when the access panel has been removed
Rear Port Control Cover	Yes, locks rear IO cables to prevent cable theft
Serial, Parallel, USB, Audio, Network, Enable/Disable Port Control	Yes, enables or disables serial, USB, audio, and network ports
Removable Media Write/Boot Control	Yes, prevents ability to boot from removable media on supported devices (and can disable writes to media)
Power-On Password	Yes, prevents an unauthorized person from booting up the workstation
Setup Password	Yes, prevents an unauthorized person from changing the workstation configuration
3.3V Aux Power LED on System PCA	Yes
NIC LEDs (integrated) (Green & Amber)	Yes
CPUs and Heatsinks	A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be removed. CPU removal is tool-less
Power supply diagnostic LED	No
Power Button	Yes, ACPI multi-function
Power LED	Yes, blue (normal), red (fault)
Hard drive activity LED	Yes, green
Internal speaker	Yes
System/Emergency ROM Flash Recovery	Recovers corrupted system BIOS.
OS CD (Restore OS CD)	Restores computer to its original factory shipping Operating System - No recovery CDs will ship with Windows XP, Vista or Linux - an ISO image will be available on an HD partition.



Cooling Solutions	Air cooled forced convection			
Power Supply Fans	92 mm x 92 mm x 25 mm 4-wire PWM (non-serviceable)			
CPU Heatsink Fan(s)	Not applicable- CPU heatsink is passive.			
Chassis Fans	92 mm x 92mm x 25 mm 4-wire PWM			
Memory Fans	No			
Access Panel Key Lock	No			
ACPI-Ready Hardware	Advanced Configuration and Power Management Interface (ACPI).			
	 Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system 			
Integrated Chassis Handles	No			
Power Supply	Tool-less			
PCI Card Retention	Yes, rear (all), middle (none), front (none)			
Flash ROM	Yes			
Diagnostic Power Switch LED on board	Yes			
Clear Password Jumper	Yes			
Clear CMOS Button	Yes			
CMOS Battery Holder for easy Replacement	Yes			
DIMM Connectors for easy Upgrade	Yes			

BIOS			
BIOS 32-bit Services	Standard BIOS 32-bit Service Directory Proposal v0.4		
PCI 3.0 Support	Full BIOS support for PCI Express through industry standard interfaces.		
ATAPI	ATAPI Removable Media Device BIOS Specification Version 1.0.		
BBS	BIOS Boot Specification v1.01.		
WMI Support	WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.		
BIOS Boot Spec 1.01+	Provides more control over how and from what devices the workstation will boot.		
BIOS Power On	Users can define a specific date and time for the system to power on.		
ROM Based Computer Setup Utility (F10)	Review and customize system configuration settings controlled by the BIOS.		
System/Emergency ROM Flash Recovery with Video	Recovers system BIOS in corrupted Flash ROM.		
Replicated Setup	Saves BIOS settings to USB flash device in human readable file. Repset.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setup).		
SMBIOS	System Management BIOS 2.6, for system management information.		
Boot Control	Disables the ability to boot from removable media on supported devices.		



Memory Change Alert	Alerts management console if memory is removed or changed.			
Thermal Alert	Monitors the temperature state within the chassis. Three modes:			
	 NORMAL - normal temperature ranges. ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown. SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs. 			
Remote ROM Flash	Provides secure, fail-safe ROM image management from a central network console.			
ACPI (Advanced Configuration and Power Management Interface)	Allows the system to enter and resume from low power modes (sleep states). Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.			
Ownership Tag	A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.			
Remote Wakeup/Remote Shutdown	System administrators can power on, restart, and power off a client computer from a remote location.			
ASF 2.0 Compliant	Allows workstation status to be monitored on a remote console.			
Instantly Available PC (Suspend to RAM - ACPI sleep state S3)	Allows for very low power consumption with quick resume time.			
Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)	Allows a new or existing system to boot over the network and download software, including the operating system.			
ROM revision levels	Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS) so that management SW applications can use and report this information.			
System board revision level	Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified.			
Start-up Diagnostics (Power-on Self-Test)	Assesses system health at boot time with selectable levels of testing.			
Auto Setup when new hardware installed	System automatically detects addition of new hardware.			
Keyboard-less Operation	The system can be booted without a keyboard.			
Localized ROM Setup	Common BIOS image supports System Configuration Utility (F10 Setup) menus in 12 languages with local keyboard mappings.			
Asset Tag	The user or MIS to set a unique tag string in non-volatile memory.			
Per-slot Control	Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually.			
Adaptive Cooling	Control parameters are set according to detected hardware configuration for optimal acoustics.			
Pre-boot Diagnostics	(Pre-video) critical errors are reported via beeps and blinks on the power LED.			
AMT 6.0 Compliant	Allows workstation status to be monitored on a remote console			
Industry Standard Specification Support				
Industry Standard	Revision Supported by the BIOS			
ACPI	Advanced Configuration and Power Management Interface, Version 1.0			
ASF	Alert Standard Format Specification, Version 2.0			



System Technical Specifications

ATA (IDE)	AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b		
CD Boot	"El Torito" Bootable CD-ROM Format Specification Version 1.0		
EDD	 Enhanced Disk Drive Specification Version 1.1 BIOS Enhanced Disk Drive Specification Version 3.0 		
EHCI	Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0		
PCI	PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7		
PCI Express	PCI Express Base Specification, Revision 2.0		
PMM	POST Memory Manager Specification, Version 1.01		
SATA	 Serial ATA Specification, Revision 1.0a Serial ATA 3 Gb/s: Extensions to Serial ATA 1.5 Gb/s, Revision 1.0 		
SPD	PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B		
TPM	Trusted Computing Group TPM Specification Version 1.2		
USB 1.1	Universal Serial Bus Revision 1.1 Specification		
USB 2.0	Universal Serial Bus Revision 2.0 Specification		
SMBIOS	System Management BIOS Reference Specification, Version 2.6		

System Software M	anagement and Updating			
HP Client Management Solutions	Visit: http://www.hp.com/go/easydeploy			
Product Change Notification	 Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile. PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition. Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call technical support. 			
Support Software CD & WWW	Yes			
HP Client Manager	Visit: http://www.hp.com/go/easydeploy			
System Software Manager	Visit: http://www.hp.com/go/ssm			
Social and Environ	mental Responsibility			
Eco-Label Certifications & Declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • ENERGY STAR® (energy-saving features available on selected configurations -Windows only) • US Federal Energy Management Program (FEMP) • China Energy Conservation Program			
	 IT ECO declaration Japan PC Green label* *This product conforms to the examination standards (2003 version) under JEITA's 'PC Green Label 			



Recycled Content and

Design for Recycling

The Corrugated Carton packaging material is made from 100% recycled content.

The EPE - Expanded Polyethylene packaging material is made from 100% recycled content

System Technical Spe	ecitications
	The Polyethylene low density foam packaging material is made from 100% recycled content. Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas.
	To recycle your product, please go to:
	http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office.
	Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
Batteries	Battery size: CR2032 (coin cell)
	Battery type: Lithium Metal.
	This product complies with ISO standards:
	EU Directive 91/157/EEC
	EU Directive 93/86/EEC EU Directive 93/86/EEC
	EU Directive 98/101/ EEC
	Batteries used in the product do not contain:
	Mercury greater than 5ppm by weight
	Cadmium greater than 10ppm by weight
	Lead greater than 4000ppm by weight.
Restricted Material Usage	
Ĭ	HP General Specification for the Environment at:
	http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):
	• Asbestos
	Batteries – Mercury
	Batteries – Cadmium Batteries – Lead (non-rechargeable)
	Batteries - Non-rechargeable Alkaline and Carbon-Zinc Batteries Patteries - Classification as "Not Postricted" for Transport
	 Batteries – Classification as "Not Restricted" for Transport Brominated Flame Retardants (PBBs, PBDEs, including DecaBDE)
	Brominated Flame Retardants (all BFRs in external case plastic parts)
	Cadmium and its compounds
	Certain Azo Colorants
	Chlorinated Hydrocarbons
	Chlorinated Paraffins
	Formaldehyde
	Formaldehyde – emissions
	Hexavalent Chromium and its compounds in metallic applications
	Hexavalent Chromium and its compounds in non-metallic applications
	Lead and its compounds
	• Lead in paint
	Lead in Polyvinyl Chloride (PVC) coating of external cables, wires and cords
	Mercury and its compounds
	Nickel on external surfaces One on Doubting Substances (ODS)
	Ozone Depleting Substances (ODS) Polyvedia Aramatic Hydrogorhana (RAH)
	 Polycyclic Aromatic Hydrocarbons (PAH) Perfluorooctane sulfonates (PFOS) in parts
	Perfluorooctane sulfonates (PFOS) in preparations
	 Polychlorinated Biphenyls (PCBs) and Polychlorinated Terphenyls (PCTs)
	Polychlorinated Naphthalenes
	Polyvinyl Chloride (PVC) in external case plastic parts
	Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)



,				
Packaging	HP follows these guidelines to decrease the environmental impact of product packaging:			
	 Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packo materials. 			
	 Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. 			
	 Design packaging materials for ease of alsassembly. Maximize the use of post-consumer recycled content materials in packaging materials. 			
	Use readily recyclable packaging materials such as paper and corrugated materials.			
	 Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. 			
Longevity and Upgrading	This product is designed to be upgraded, possibly extending its useful life by several years. Spare parts			
	are available throughout the warranty period and for up to 5 years after the end of production.			
Packaging Materials				
External	Corrugated 2550 g The corrugated packaging material is made from 37% recycled content.			
Internal	Polyethylene high density 160 g.			
	The Polyethylene high density packaging material is made from 100%			
	recycled content.			
End-of-Life Management	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas.			
and Recycling	To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.			
	[link to new HP white paper now in progress]			
	Global Citizenship Report: http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html			
	Eco-label certifications:			
	http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html			
	ISO 14001 certificates:			
	http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html			
Hewlett-Packard	For more information about HP's commitment to the environment:			
Corporate Environmental	Global Citizenship Report: http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html			
Information	Eco-label certifications: http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html			
	ISO 14001 certificates:			
	http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html			
Service, Support and	On-site Warranty and Service (Note 1): One and three-years, limited warranty and service offering delivers			
Warranty	on-site, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering			
	NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country. NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party			
Additional Information	hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries. HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Additional HP Care Pack Services information by product is available at: http://www.hp.com/hps/carepack. Service levels and response times for HP Care Packs may vary depending on your geographic location. • his product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive —			



System Technical Specifications

2002/95/EC.

- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE)
 Directive 2002/96/EC.
- Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.
- This product contains 0% recycled materials (by weight)
- This product is >90% recycle-able when properly disposed of at end of life.



Stable & Consistent Offerings

As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware and software designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section. HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware and software components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

Processors	Product #	Offering
	WG013AV	Intel Core i5-650 3.2 4MB/1333 DC CPU
	WG015AV	Intel Core i5-670 3.46 4MB/1333 DC CPU
	WG019AV	Intel Xeon X3450 2.66 8MB/1333 QC CPU
Hard Drives	Product #	Offering
	WF996AV	HP 250GB SATA 7200 1st HDD
	WG002AV	HP 250GB SATA 7200 2nd HDD
	WF998AV	HP 500GB SATA 7200 1st HDD
	WG004AV	HP 500GB SATA 7200 2nd HDD
Graphics	Product #	Offering
•	WF977AV	NVIDIA Quadro NVS 295 256MB Graphics
	WF978AV	NVIDIA Quadro NVS 295 256MB Graphics (2nd)
Memory	Product #	Offering
	WG029AV	HP 2GB (2x1GB) DDR3-1333 ECC RAM
	WG033AV	HP 4GB (2x2GB) DDR3-1333 ECC RAM
	WG037AV	HP 8GB (4x2GB) DDR3-1333 ECC RAM
Optical and Removable	Product #	Offering
Storage	WG007AV	HP 16X DVD+-RW SuperMulti SATA Drive
Input Devices	Product #	Offering
•	VG956AV	HP USB Standard Keyboard
	VB274AV	HP USB Optical Scroll Mouse
Operating Systems	Product #	Offering
	WF962AV	MS Windows 7 Professional 64-bit OS



Technical Specifications - Processors

Processors

Intel® Pentium® Processor G6950 2.8 GHz, 3MB cache, 1066 MHz memory, Dual-Core Intel® Core™ Processor i3-530 2.93 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT Intel Core Processor i3-540 3.06 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT Intel Core Processor i3-550 3.20 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT Intel Core Processor i5-650 3.20 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT, Turbo Intel Core Processor i5-660 3.33 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT, Turbo Intel Core Processor i5-670 3.46 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT, Turbo Intel Core Processor i5-680 3.60 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT, Turbo Intel Core Processor i5-680 3.60 GHz, 4MB cache, 1333 MHz memory, Dual-Core, HT, Turbo

Intel Core Processor i5-750 2.66 GHz, 8 MB cache, 1333 MHz memory, Quad-Core, Turbo Intel Core Processor i7-870 2.93 GHz, 8 MB cache, 1333 MHz memory, Quad-Core, HT, Turbo Intel Core Processor i7-880 3.06 GHz, 8 MB cache, 1333 MHz memory, Quad-Core, HT, Turbo

Intel Xeon Processor X3430 2.40 GHz, 8MB cache, 1333 MHz memory, Quad-Core, Turbo Intel Xeon Processor X3440 2.53 GHz, 8MB cache, 1333 MHz memory, Quad-Core, HT, Turbo Intel Xeon Processor X3450 2.66 GHz, 8MB cache, 1333 MHz memory, Quad-Core, HT, Turbo Intel Xeon Processor X3460 2.80 GHz, 8MB cache, 1333 MHz memory, Quad-Core, HT, Turbo Intel Xeon Processor X3470 2.93 GHz, 8MB cache, 1333 MHz memory, Quad-Core, HT, Turbo Intel Xeon Processor X3480 3.06 GHz, 8MB cache, 1333 MHz memory, Quad-Core, HT, Turbo

Technical Specifications - Hard Drives

SATA (Serial ATA) Hard Drives for HP Workstations 300GB SATA Capacity 10K rpm SFF Height in 3.5" Frame Width HDD

 Capacity
 300,069,052,416 bytes

 Height
 1 in; 2.54 cm

 Media Diameter
 2.5 in; 6.36 cm

 Physical Size
 4.0 in; 10.17 cm

Interface Serial ATA (3.0 Gb/s), Native Command Queuing enabled

Synchronous Transfer Rate (Maximum)

Logical Blocks

Buffer 16 MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average0.7 ms (maximum)Average
9.5 ms

586,072,368

Up to 300MB/s

settling) Full Stroke
Rotational Speed 10,000 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

 160GB SATA Capacity
 160,041,885,696 bytes

 10K rpm SFF Height
 1 in; 2.5 cm

in 3.5" Frame Width Media Diameter 2.5 in; 6.36 cm Physical Size 4 in; 10.2 cm

Interface Serial ATA (1.5 Gb/s), Native Command Queuing enabled

Synchronous Transfer Up to 300 MB/s Rate (Maximum)

Buffer 16 MB

Seek Time (typical reads, Single Track 0.7 ms (maximum)

includes controller overhead, including settling)

Average 4.4 ms

Full Stroke 9.5 ms

Rotational Speed 10,000 rpm Logical Blocks 312,581,808

Operating Temperature 41° to 131° F (5° to 55° C)

 1000GB
 Capacity
 1,000,204,886,016 bytes

 (1TB) SATA
 Height
 1 in; 2.5 cm

7200 rpm 3.0Gb/s 3.5" Width Media Diameter 3.5 in; 8.9 cm Physical Size 4 in; 10.2 cm

Interface Serial ATA (3.0 Gb/s), Native Command Queuing enabled

Synchronous Transfer Up to 300 MB/s

Rate (Maximum)

Buffer 32 MB



Technical Specifications - Hard Drives

Seek Time (typical reads, Single Track 2 ms includes controller Average 11 ms overhead, including **Full Stroke** 21 ms settling)

7,200 rpm Rotational Speed 1,953,525,168 Logical Blocks

Operating Temperature 41° to 131° F (5° to 55° C)

500GB SATA Capacity 500,107,862,016 bytes

7200 rpm 3Gb/s 3.5" HDD

Height 1 in; 2.5 cm Width

Media Diameter 3.5 in; 8.9 cm Physical Size 4 in; 10.2 cm

Interface Serial ATA (3.0 Gb/s), Native Command Queuing enabled

Synchronous Transfer 300 MB/s

Rate (Maximum)

Buffer 16 MB

Seek Time (typical reads, Single Track 2 ms includes controller Average 11 ms overhead, including Full Stroke 21 ms settling)

7,200 rpm Rotational Speed 976,773,168 Logical Blocks

Operating Temperature 41° to 131° F (5° to 55° C)

320GB SATA Capacity 320,072,933,376 bytes

7200 rpm 3Gb/s 3.5" **HDD**

0.98 in; 2.5 cm Height

Width Media Diameter 3.5 in; 8.9 cm Physical Size 4.0 in; 10.17 cm

300 MB/s

Interface Serial ATA (3.0 Gb/s), Native Command Queuing enabled

Synchronous Transfer Rate (Maximum)

Buffer

Seek Time (typical reads, Single Track 2 ms includes controller Average 12 ms overhead, including Full Stroke 21 ms settling)

8 MB

Rotational Speed 7,200 rpm Logical Blocks 625,142,448

Operating Temperature 41° to 131° F (5° to 55° C)

250GB SATA Capacity 250,059,350,016 bytes

7200 rpm Height 1 in; 2.54 cm



Technical Specifications - Hard Drives

3Gb/s 3.5" Width Media Diameter 3.5 in; 8.9 cm Physical Size 4.0 in; 10.17 cm

Interface Serial ATA (3.0 Gb/s), Native Command Queuing enabled

Synchronous Transfer 300 MB/s Rate (Maximum)

Buffer 8 MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average2 msAverage11 msFull Stroke21 ms

Rotational Speed 7,200 rpm Logical Blocks 488,397,168

Operating Temperature 41° to 131° F (5° to 55° C)

160GB SATA Capacity 160,041,885,696 bytes

7200 rpm 3Gb/s 3.5" HDD

Height

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.2 cm

1 in; 2.5 cm

Interface Serial ATA (3.0 Gb/s), Native Command Queuing enabled

Synchronous Transfer 300 MB/s Rate (Maximum)

Buffer 8 MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average2 msAverage11 msFull Stroke21 ms

Rotational Speed 7,200 rpm Logical Blocks 312,581,808

Operating Temperature 41° to 131° F (5° to 55° C)

Technical Specifications - Graphics

Integrated Intel Graphics Media Accelerator HD

Form Factor

Graphics Controller

Bus Type

Memory

Integrated

Intel Integrated Graphics Media Accelerator HD

PCI Express x16

Graphics memory is shared with system memory. Graphics memory usage varies depending on the amount of system memory installed, BIOS settings, operating system, and system load. 32 MB is pre-allocated for graphics use

at system boot time. Additional memory can be allocated at boot time by the BIOS for PAVP (Protected Audio Video Playback) support for playback of protected video content. For Vista, use of PAVP heavy mode preallocates an

additional 96MB.

Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between

graphics and system memory use.

Connectors Z200; 1 Single Link DVI-I, 1 DP

Z200 SFF; 1 VGA, 1 DP

Graphics adapters are orderable as an accessory as necessary.

RAMDAC Integrated, 350 MHz

Display Output Two DisplayPort outputs drive two digital displays up to 2560 x 1600

NOTE: This card supports up to two displays

Display Output Z200: Integrated dual independent monitor support facilitated via one DVI

port and one DisplayPort integrated on the back plane of the system board and presented as part of the rear I/O set of interfaces. Second DVI supported via optional DisplayPort to DVI-D adapter. VGA support via optional DVI to

VGA adapter or DisplyPort to VGA adapter.

Z200 SFF: Integrated dual independent monitor support facilitated via one VGA port and one DisplayPort integrated on the back plane of the system board and presented as part of the rear I/O set of interfaces. Second VGA supported via optional DisplayPort to VGA adapter. DVI support via optional

DisplayPort to DVI adapter.

Intel HD graphics can provide audio to displays supporting audio over

DisplayPort or HDMI (via DisplayPort to HDMI adapter)

Supported Graphics APIs Microsoft DirectX 10, OpenGL 2.1

Technical Specifications - Graphics

NVIDIA Quadro NVS 295 Form Factor

256MB Graphics Card

2.731 inches (H) \times 6.600 inches (L), Half-Height

Graphics Controller NVIDIA Quadro NVS 295 Graphics Board **Bus Type** PCI Express x16, Generation 2.0

Memory 256 MB GDDR3 SDRAM unified graphics memory

Connectors 2 DisplayPort

Comes with 2 DisplayPort to DVI-D Adapters

('DisplayPort to VGA' and 'DisplayPort to DL DVI' adapters available as an

accessory)

Maximum Resolution Two DisplayPort outputs drive two digital displays up to 2560 x 1600

NOTE: This card supports up to two displays

Display Output Drives DisplayPort enabled digital displays at resolutions up to 2560

 \times 1600 at 60 Hz with reduced blanking

Drives DVI enabled digital displays at resolutions up to 1920×1200 at 60 Hz with reduced blanking (through DisplayPort to DVI-D (single

link) cable)

Supported Graphics APIs OpenGL 3.0

DirectX 10.0

Available Graphics

Drivers

Genuine Windows Vista Business (64-bit and 32-bit) Microsoft Windows XP Professional (64-bit and 32-bit)

Red Hat Enterprise Linux(RHEL) WS4 & 5 Desktop/Workstation

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Novell SUSE Linux Enterprise drivers may be obtained from: ftp://download.nvidia.com/novell or http://www.nvidia.com

22.69 Watts Power consumption

NVIDIA Quadro FX 380 LP 512MB Graphics Card

Form Factor

Graphics Controller

Maximum Resolution

Low Profile 2.7" x 6.6" single slot board

NVIDIA Quadro FX 380 LP Graphics Board

Bus Type PCI Express x16, Generation 2.0

Memory 512 MB GDDR3 SDRAM unified graphics memory

Connectors 1 DisplayPort, 1 Dual-Link DVI-I

One DisplayPort to DVI-I adapter included

 DisplayPort output drives a digital display at resolutions up to 2560 x 1600 @ 60Hz

Dual-link DVI-I output drives a digital display at resolutions up to 2560 x 1600 @ 60Hz

NOTE: This card supports up to two displays

RAMDAC Dual Internal 400 MHz DAC

Shading architecture Full Shader Model 4.1 (OpenGL 3.2/DirectX 10 class)

Long fragment programs (unlimited instructions)

Long vertex programs (unlimited instructions)



Technical Specifications - Graphics

- Looping and subroutines (up to 256 loops per vertex program)
- Dynamic flow control
- Conditional execution

Supported graphics APIs

OpenGL 3.2 DirectX 10.1

Available graphics drivers Genuine Windows 7 Professional (64-bit and 32-bit) Genuine Windows Vista Business (64-bit and 32-bit) Microsoft Windows XP Professional (64-bit and 32-bit) Red Hat Enterprise Linux(RHEL) 5 Desktop/Workstation SUSE Linux Enterprise Desktop 11 (64-bit and 32-bit)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Novell SUSE Linux Enterprise drivers may be obtained from: ftp://download.nvidia.com/novell or http://www.nvidia.com

High-Resolution **Antialiasing**

- Rotated Grid Full-Scene Antialiasing (RG FSAA)
- 32x FSAA dramatically reduces visual aliasing artifacts or "jaggies" at resolution up to 1920x1200

Parallel Processor Cores Power consumption

28 Watts

16

ATI FirePro V3800 512MB Graphics Card Form Factor

2.71 in (H) x 6.61 in (L) "Single-Wide"

Graphics Controller

ATI FirePro V3800 Graphics Board PCI Express x16, Generation 2.0

Bus Type Memory

512 MB DDR3 SDRAM

1 DL DVI, 1 DP output

Connectors

One DP to DVI adapter included

Maximum Resolution

Up to two digital displays at resolutions up to 2560 x 1600 @ 60Hz or two analog displays, one at resolutions up to 2048 x 1536 @ 85Hz, the other at

up to 1920 x 1200 @ 60Hz (165 MHz dot clock) NOTES: This card supports up to two displays

Use of more than two displays on Linux requires support for xrandr 1.2 or

greater in the X server

RAMDAC

400 MHz DAC, 10-bits per channel

Image Quality Features

- Full 30-bit display pipeline for more accurate color reproduction superior image quality (30-bit monitor required for full 30-bit display)
- Advanced video capabilities, including high fidelity gamma, color correction and scaling
- Dedicated hardware (UVD2) for H.264, VC-1, and MPEG2 decode
- Shading architecture
- Support for Full Shader Model 5.0
- 400 Stream Processing Units
- Dynamic load balancing and resource allocation for vertex, geometry, and pixel shaders
- Common instruction set and texture unit access supported for all types of shaders
- Dedicated branch execution units and texture address processors



Technical Specifications - Graphics

• Anti-aliases Shaders and Textures as well as Polygon Edges

Supported graphics APIs DirectX 11, OpenGL 3.2, OpenCL 1.0 and full implementation of

DirectCompute 11

(OpenCL[™] compliant driver and SDK release scheduled in 2010)

Available graphics drivers Genuine Windows 7 Professional (64-bit and 32-bit)

Genuine Windows Vista Business (64-bit and 32-bit) Microsoft Windows XP Professional (64-bit and 32-bit) Red Hat Enterprise Linux (RHEL) 4 and 5 Desktop/Workstation

SUSE Linux Enterprise Desktop 11 (64-bit and 32-bit)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Parallel Processor Cores 400 Stream processors (675 single-precision GFLOPS performance)

Power consumption 43 Watts



Technical Specifications - Multimedia and Audio Devices

HP Thin USB Powered **Speakers**

Frequency Response (-3dB, 24-bit/96kHz input) FO to 20kHz

Dimensions

Speakers: 14.52 x 9.50 x 2.45 cm (5.72 x 3.74 x 0.96 in) per speaker

On/Off/Volume Controls Right side of right speaker Power LED Front of right speaker (green) Watts 2/3 watt (normal/maximum)

Net weight 0.68 lbs (0.31kg)

Temperature (operating): -10° to 40° C (14° to 104° F) Environmental (all

conditions non-Relative Humidity 40% to 90%

condensing) (operating):

Speaker cable length Input cord: 1800mm±35mm (5.91 ft)

> L-channel cord: 1000mm±35mm (3.28 ft) USB cord: 1800mm±35mm (5.91 ft)

Color **HP** Carbonite

Kit Contents One pair of HP Thin USB Powered Speakers with attached audio signal and

USB power cables for connecting to your PC

HP Warranty documentation

Integrated Intel/Realtek HD ALC261 Audio

Minimum System Requirements

Kit Contents

Integrated

USB Powered

Speakers Power LED

Yes

Yes

Frequency response Yes

Audio Jacks Front panel microphone in and headphone out - fixed usage.

Rear panel line in and line out jacks - jacks are retaskable

One Line-In (12-K ohm Input Impedance)*

*External Speakers need to be powered externally.

Sampling 3 stereo ADCs support 16/20-bit PCM format with

44.1K/48K/96kHz sample rate

2 stereo DAC supports 16/20/24-bit PCM format with

44.1K/48K/96K/192kHz sample rate

(software)

Wavetable Syntheses Yes – GM and FM Midi Support, Direct Music and Down

Loadable Soundset (4 Meg DLS Level 1 and 2 Support)

Frequency Response No Input sensitivity Yes Cable Yes Dimensions (H x W x Yes

D)

Creative X-Fi

1.5 W

Titanium Audio Card, PCle

24-bit Analog-to-Yes Digital conversion of analog inputs



Technical Specifications - Multimedia and Audio Devices

24-bit Digital-to- No
Analog conversion of
stereo digital sources
24-bit Digital-to- Yes
Analog conversion of
stereo digital sources



Technical Specifications - Optical and Removable Storage

HP DVD-ROM Drive Description 5.25-inch, half-height, tray-load

> Mounting Orientation Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 15.0 x 4.4 x 20.3 cm (5.9 x 1.7 x 8.0 in)

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB Double layer: Up to

8.5 GB

Access Times DVD-ROM Single Layer < 140 ms (typical)

> CD-ROM Mode 1 < 125 ms (typical) Full Stroke DVD < 250 ms (seek) Full Stroke CD < 210 ms (seek)

Power Source SATA DC power receptacle

> DC Power Requirements $5 \text{ VDC} \pm 5\%\text{-}100 \text{ mV ripple p-p}$

 $12 \text{ VDC} \pm 5\%$ -200 mV ripple p-p

DC Current 5 VDC - < 1000 mA typical, < 1600 mA

maximum

12 VDC - < 600 mA typical, < 1400 mA

maximum

10% to 90%

30° C (86° F)

Operating Environmental Temperature 5° to 50° C (41° to 122° F)

(all conditions non-

Relative Humidity condensing) Maximum Wet Bulb

Temperature

Operating Systems

Supported

Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*,

Windows 2000, Windows XP Professional or

Windows XP Home 32*.

Red Hat Enterprise Linux(RHEL) WS4, 5

Desktop/Workstation Novell SLED 10 & SLED 11

No driver is required for this device. Native support is provided by the operating system.

* Certain Windows Vista product features require advanced or additional hardware. See http://www.microsoft.com/windowsvista/

getready/hardwarereqs.mspx and http://www.microsoft.com/windowsvista/

getready/capable.mspx for details. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit:

http://www.windowsvista.com/upgradeadvisor. For Windows Vista system requirements, visit: http://www.windowsvista.com/systemrequirements.

HP DVD+/-RW Drive

Description

5.25-inch, half-height, tray-load



Technical Specifications - Optical and Removable Storage

Mounting Orientation Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 15.0 x 4.4 x 20.3 cm (5.9 x 1.7 x 8.0 in)

Disc Formats DVD-RAM

DVD+RDVD+RWDVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

8.5 GB DL or 4.7 GB standard Disc Capacity DVD-ROM

> Full Stroke DVD < 250 ms (seek) Full Stroke CD < 210 ms (seek)

Maximum Data Transfer CD ROM Read

Rates

CD-ROM, CD-R Up to 40X

CD-RW Up to 32X

DVD ROM Read DVD-RAM Up to 12X

> Up to 8X DVD+RWDVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 16X DVD-ROM DL Up to 8X DVD+RUp to 16X DVD-R Up to 16X

SATA DC power receptacle Power Source

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

 $12 \text{ VDC} \pm 5\%$ -200 mV ripple p-p

DC Current 5 VDC -1000 mA typical, 1600 mA maximum

12 VDC -600 mA typical, 1400 mA maximum

Operating Environmental Temperature 5° to 50° C (41° to 122° F)

(all conditions noncondensing)

Relative Humidity

10% to 90%

Maximum Wet Bulb

Temperature

30° C (86° F)

Operating Systems

Supported

Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or

Windows XP Home 32*.

Red Hat Enterprise Linux(RHEL) WS4, 5

Desktop/Workstation Novell SLED 10 & SLED 11

No driver is required for this device. Native support

is provided by the operating system.



Technical Specifications - Optical and Removable Storage

*Certain Windows Vista product features require advanced or additional hardware. See http://microsoft.com/windowsvista/getready/hardwarereqs.mspx and http://www.microsoft.com/windowsvista/getready/capable.mspx for details. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit:

http://www.windowsvista.com/upgradeadvisor. For Windows Vista system requirements, visit:

http://www.windowsvista.com/systemrequirements

* LightScribe functionality is not natively supported by Linux distributions. Customers may download LightScribe Linux drivers from: http://www.lightscribe.com/ downloadSection/linux/index.aspx

Kit Contents

HP SATA SuperMulti LightScribe DVD Writer drive, LightScribe software, Roxio Easy Media Creator software, Intervideo WinDVD Software, installation guide, and DVD+R media.

HP 22-in-1 Media Card Reader Description

The Media Card Reader device uses the same physical form factor and mounting as a Floppy Disk Drive. The device connects to a 2x5 two-channel USB header on the motherboard of the system. There is no USB controller card provided. Please see the Disc Formats section below for a list of flash memory card formats that are supported.

Mounting Orientation

The Media Card Reader can be mounted in a dedicated Floppy Drive bay (if the chassis provides one) or in an appropriate Optical Bay adapter. It will operate in any orientation.

Interface Type

USB 2.0 (one channel dedicated to the separate USB port; one channel

dedicated to the flash memory card slots)

Dimensions (WxHxD)

124.5 x 101.6 x 25.4 mm (4.9 x 4.0 x 1.0 in)

Disc Formats

xD-Picture Micro SD Micro SDHC SD

SD SDHC Mini SD Mini SDHC

MultiMediaCard (MMC)

Reduced Size MultiMediaCard (RS MMC)

MultiMedia Card 4.2 (MMC Plus, including MMC Plus HC)

Reduced Size MultiMedia Card 4.2 (MMC Mobile, including MMC Mobile

HC)

CompactFlash Card Type I CompactFlash Card Type II

MicroDrive



Technical Specifications - Optical and Removable Storage

Memory Stick (MS)

MagicGate Memory Stick (MG) MagicGate Memory Stick Duo

Memory Stick Select

Memory Stick Duo (MS Duo) Memory Stick PRO (MS PRO)

Memory Stick PRO Duo (MS PRO Duo)

Memory Stick PRO-HG Duo

Two additional formats are usable with adapters (not supplied):

MMC Micro

Memory Stick Micro (M2)

HP Blu-Ray Writer	Description	5.25-inch, half-height, tray-load				
	Mounting Orientation	ation Either horizontal or vertical SATA				
	Interface Type					
	Dimensions (WxHxD)	Dimensions (WxHxD) 15.0 x 4.4 x 20.3 cm (5.9 x 1.7 x 8.0 in)				
	Disc Formats	BD-ROM BD-R				
		BD-RE DVD-RAM				
		DVD+R				
		DVD+RW				
		DVD+R DL				
		DVD-R DL DVD-R				
		DVD-RW				
		CD-R				
	D: C ::	CD-RW	0.5.00.01 4.7.00			
	Disc Capacity	DVD-ROM	8.5 GB DL or 4.7 GB standard			
		Blu-ray	50 GB DL or 25 GB standard			
		Full Stroke DVD	< 250 ms (seek)			
		Full Stroke CD	< 210 ms (seek)			
		Blu-ray	Blu-ray	056 / 006		
		Startup Time (Time to drive ready from tray loading)	BD-ROM (SL/DL)	25\$ / 28\$		
			BD-R (SL/DL)	25\$ / 28\$		
			BD-RE (SL/DL)	25\$ / 28\$		
			DVD-ROM (SL/DL)	185 / 185		
			DVD-R (SL/DL)	25S / 25S		
			DVD-RW	25\$		
			DVD+R (SL/DL)	25\$ / 25\$		
			DVD+RW	25S		
			DVD-RAM	45S		
			CD-ROM	45S		

CD-ROM

CD-R

Maximum Data Transfer CD ROM Read

Rates

Up to 40X

Up to 40X

Technical Specifications - Optical and Removable Storage

nons - Oplicai and Rem	ovable Slorage			
		CD-RW	Up to 40X	
	DVD ROM Read	DVD-RAM	Up to 5X	
		DVD+RW	Up to 10X	
		DVD-RW	Up to 10X	
		DVD+R DL	Up to 8X	
		DVD-R DL	Up to 8X	
		DVD-ROM	Up to 16X	
		DVD-ROM DL	Up to 8X	
		DVD+R	Up to 12X	
		DVD-R	Up to 12X	
	Blu-Ray	BD-ROM	Up to 6X	
		BD-ROM DL	Up to 4.8X	
		BD-R	Up to 6X	
		BD-R DL	Up to 4.8X	
		BD-R	Up to 6X	
		BD-RE SL/DL	Up to 4.8X	
Power	Source	SATA DC power receptacle		
	DC Power Requirements	5 VDC \pm 5%-100 mV ripple p-p 12 VDC \pm 10%-100 mV ripple p-p		
	DC Current	5 VDC -900 mA typical, 12 VDC -1000 mA typic		
Operating Environmental	Temperature	5° to 50° C (41° to 122° F)		
(all conditions non-	Relative Humidity	15% to 80%		
condensing)	Maximum Wet Bulb Temperature	30° C (86° F)		
	Operating Systems Supported	Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or Windows XP Home 32*. Red Hat Enterprise Linux(RHEL) WS3, WS4, 5 Desktop/Workstation Novell SLES 9 & SLE 10		
		No driver is required for support is provided by the		
	Kit Contents	HP Blue Laser RW Drive Roxio Easy Media Creat WinDVD Software, insta	or software, Intervideo	
Disclaimer As Blu-Ray is a new format containing new technologies, certal connection, compatibility and/or performance issues may arise constitute defects in the product. Flawless playback on all system guaranteed. In order for some Blu-Ray titles to play, they may or HDMI digital connection and your display may require HDMI digital connection.		s may arise, and do not on all systems is not they may require a DVI equire HDCP support.		



HD-DVD movies cannot be played on this workstation.

Technical Specifications - Optical and Removable Storage

HP 22-in-1 3.5 JB Media Description

Card Reader w/1394a

The Media Card Reader device uses the same physical form factor and mounting as a Floppy Disk Drive. The device connects to a 2x5 two-channel USB header on the motherboard of the system. There is no USB controller card provided. Please see the Disc Formats section below for a list of flash memory card formats that are supported.

Mounting Orientation The Media Card Reader can be mounted in a dedicated Floppy Drive bay (if

the chassis provides one) or in an appropriate Optical Bay adapter. It will

operate in any orientation.

Interface Type USB 2.0 (one channel dedicated to the separate USB port; one channel

dedicated to the flash memory card slots)

Dimensions (WxHxD) 4.9 x 4.0 x 1.0 in (124.5 x 101.6 x 25.4 mm)

Supported Media Types xD-Picture

Micro SD Micro SDHC

SD SDHC Mini SD Mini SDHC

MultiMediaCard (MMC)

Reduced Size MultiMediaCard (RS MMC)

MultiMedia Card 4.2 (MMC Plus, including MMC Plus HC)

Reduced Size MultiMedia Card 4.2 (MMC Mobile, including MMC Mobile

HC)

CompactFlash Card Type I CompactFlash Card Type II

MicroDrive

Memory Stick (MS)

MagicGate Memory Stick (MG) MagicGate Memory Stick Duo

Memory Stick Select

Memory Stick Duo (MS Duo) Memory Stick PRO (MS PRO)

Memory Stick PRO Duo (MS PRO Duo)

Memory Stick PRO-HG Duo

Two additional formats are usable with adapters (not supplied):

MMC Micro

Memory Stick Micro (M2)



Technical Specifications - Controller Cards

HP FireWire/IEEE 1394a Data Transfer Rate PCI Card

Burst Data Rate up to 400 Mbps

Device Interface Protocol IEEE-1394a

Devices Supported IEEE-1394 compliant devices

Bus Type PCI card with brackets for low profile and full height PCI slots.

Certification Level FCC Part 15B, cULus 60950, CE Mark EN55022B(1995)/EN55024-1998

STD, Taiwan BSMI CNS13438, Korea MIC

Ports Two IEEE 1394 6-Pin Connector (Rear)

Internal Connectors One 10-Pin (9 Contacts) Custom Connector

System Requirements Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista

Home Basic 32*, Windows 2000, Windows XP Professional or Windows XP Home 32*. No driver is required for this device. Native support is provided

by the operating system.

* Certain Windows Vista product features require advanced or additional hardware. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: http://www.windowsvista.com/upgradeadvisor. For Windows Vista system requirements, visit:

http://www.windowsvista.com/systemrequirements.

Pentium II 266 or above

128-MB RAM 1-GB Hard Drive CD-ROM drive Built-in sound system Available PCI slot

Temperature - Operating

Temperature - Storage

50° to 131° F (10° to 55° C) -22° to 140° F (-30° to 60° C)

Relative Humidity -

20% to 80%

Operating

Operating Systems

Supported

Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or Windows XP

Home 32*

* Certain Windows Vista product features require advanced or additional hardware. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: http://www.windowsvista.com/upgradeadvisor. For Windows Vista system requirements, visit:

http://www.windowsvista.com/systemrequirements.



Technical Specifications - Networking and Communications

Broadcom (5761) NetXtreme Gigabit Ethernet Plus NIC Connector RJ-45

Controller Broadcom 5761 PCI-Express LAN Controller

Memory 8 MB NVRAM serial Flash
Data Rates Supported 10/100/1000 Mbps

Compliance IEEE 802.1P, 802.1Q, 802.2, 802.3, 802.3AB, 802.3u, and 802.3x

Bus Architecture PCI-Express

Data Path Width Single Channel PCI-Express

Data Transfer Mode Bus Master DMA

Hardware Certifications FCC class B, Canada and US NRTL Mark, C-Tick for Australia, BSMI for

Taiwan, VCCI for Japan, MIC for Korea, GOST for Russia, UL listed

(E212044), European Union Notice (CE 0682)

Power Requirement 1.8W @ 3.3V

Boot ROM Support Yes

Network Transfer Mode Full-duplex

Half-duplex (not available for the 1000BASE-T transceiver)

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Operating Temperature 32° to 131°F (0° to 55° C)

Operating Humidity

131° F (55° C) with 5% to 95% non-condensing humidity

7 cm x 10.5 cm (2.75 in x 4.13 in), low profile compatible

Operating System Driver Windows Vista 32-bit SP1,

Support

Windows Vista 32-bit SP1, Windows Vista x64 SP1, Windows XP 32 bit

professional, Windows XP x64

Red Hat Enterprise Linux(RHEL) WS4, 5 Desktop/Workstation

Novell SLED 10 & 11

Management Capabilities ACPI, WOL and DMI 2.0, PXE 2.0, WfM 2.0, Broadcom mgmt utility,

ASF2.0, DASH 1.0 and DASH 1.1 profiles

Kit Contents Broadcom NetXtreme Gigabit Ethernet Plus NIC, Broadcom NetXtreme

Gigabit Ethernet Plus NIC USB Cable Assembly, CD, drivers, quick install

guide, product warranty statement

Technical Specifications - Networking and Communications

Intel Gigabit CT Desktop Connector

NIC

Connector RJ-45

Controller Intel WG82574L Gigabit Ethernet Controller

Memory Integrated Dual 48K configurable transmit receive FIFO Buffers

Data Rates Supported 10/100/1000 Mbps

Compliance IEEE 802.1P, 802.1Q, 802.2, 802.3, 802.3AB and 802.3u compliant,

802.3x flow control

Bus Architecture PCI-E 1.0a

Data Path Width X1, 250 MB/s, Bi-directional interface

Data Transfer Mode Bus-master DMA

Hardware Certifications FCC, B, CE, TUV- cTUVus Mark Canada and United States, TUV- GS Mark

for European Union

Power Requirement Aux 3.3V, 3.0 Watts in 1000base-T and 2.0 Watts in 100Base-T

Boot ROM Support Yes

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Operating Temperature 32° to 131°F (0° to 55° C)
Operating Humidity 85% at 131° F (55° C)

Dimensions 12.1 x 5.7 x 2.0 cm (4.75 x 2.25 x 0.8 in)

Operating System Driver

Support

Windows Vista Business 64, Windows Vista Business 32, Windows XP

Professional, Windows XP x64.

Red Hat Enterprise Linux 4, Red Hat Enterprise Linux 5.

Management Capabilities WOL, PXE, DMI, WFM 2.0

Kit Contents Intel Gigabit CT Desktop NIC, low profile bracket, CD containing Intel

PROset II NIC drivers, quick install guide, product warranty statement

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